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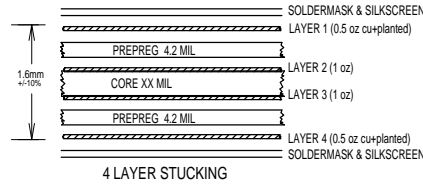
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## 5 IMPEDANCE TABLE

LAYER	TRACE (mil)	SPACING (mil)	IMPEDANCE (Single end)	IMPEDANCE (Differential)	TOLERANCE
1,4	5.0	N/A	55 OHM	N/A	+/-10%
1	6.1	8.9	N/A	90 OHM	+/-10%

## 4 LAYER STACK-UP



## REVISIONS

REV	DESCRIPTION	DATE	APPROVED
1.0	EDITION ORIGINALE	2008-**-**	***

## DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
.	12.0	+3.0/-3.0	PLATED	522
□	30.0	+3.0/-3.0	PLATED	6
○	33.0	+3.0/-3.0	PLATED	2
◦	36.0	+3.0/-3.0	PLATED	88
◌	38.0	+3.0/-3.0	PLATED	9
◐	40.0	+3.0/-3.0	PLATED	135
△	48.0	+3.0/-3.0	PLATED	6
◌	28.0	+2.0/-2.0	NON-PLATED	3
◌	38.0	+2.0/-2.0	NON-PLATED	2
□	39.0	+2.0/-2.0	NON-PLATED	3
○	47.0	+2.0/-2.0	NON-PLATED	3
A	58.0	+2.0/-2.0	NON-PLATED	1
B	79.0	+2.0/-2.0	NON-PLATED	2
C	126.0	+2.0/-2.0	NON-PLATED	2
D	138.0	+2.0/-2.0	NON-PLATED	5
•	51.0x24.0	+5.0/-5.0	PLATED	2
⊗	126.0x40.0	+5.0/-5.0	PLATED	2
⊗	126.0x40.0	+5.0/-5.0	PLATED	1
⊗	140.0x50.0	+5.0/-5.0	PLATED	2

## PCB SPECIFICATIONS:

- A. MATERIAL; FR-4, ☒ TG-170 ☐ TG-150 ☐ TG-140
- B. MATERIAL FAMILY; N/A.
- C. SOLDERMASK COLOR; ☐ GREEN ☒ BLUE ☐ RED ☐ BLACK
- D. SILKSCREEN COLOR; ☒ WHITE ☐ YELLOW ☐ BLACK
- E. SURFACE FINISH; ☒ ENIG ☐ IMMERSION SILVER ☐ IMMERSION TIN  
☐ HASL ☐ HASL(PB-FREE) ☐ GOLDEN FINGER
- F. IMPEDANCE CONTROL; ☐ NO ☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)
- G. THROUGH VIA; PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.  
PLUG MATERIAL: ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.
- H. STACK-UP; SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

## PCB REQUIREMENTS:

- THIS BOARD WILL CONFORM TO:  
IPC-A-600, CURRENT REV., CLASS II  
IPC-6012, CURRENT REV., CLASS II
- UNLESS OTHERWISE SPECIFIED ALL HOLE DIMENSIONS APPLY AFTER PLATING.  
ALL HOLES SHALL BE LOCATED WITHIN .003" DIAMETER OF TRUE POSITION.
- PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN .001 INCH MINIMUM  
AVERAGE, WITH NO READING LESS THAN .0008 BY CORROSS SECTION.
- MATERIAL FR4 RATING 94V-0 MINIMUM EPOXY GLASS LAMINATE.
- BOARD SHALL BE LPI SOLDER MASKED OVER BARE COPPER BOTH SIDES PER  
IPC-SM-840 CLASS II.
- SILKSCREEN SHALL BE PERMANENT NON-CONDUCTIVE INK AND WITH NO OVERLAP  
ON ANY COMPONENT PAD OR THROUGH HOLE.
- MFGR, TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE INK  
A. U.I. CODE D. MFGR. LOGO  
B. DATE CODE E. SUCCESSFUL ELECTRICAL BOARD TEST.  
C. FLAMMABILITY RATING
- REMOVE THE FLASHS WHICH SMALLER THAN HOLE SIZE.
- REMOVE ALL SHAPE EDGES AND BURRS .005 MAXIMUM.
- PLEASE USE THE SUPPLIED IPC 356 NETLIST TO VERIFY BOARD BEFORE  
FABRICATING BOARD.

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	LOGO				COMPANY NAME				
	DRAWN	YY-MM-DD	TITLE					PROJECT NAME *			
	CHECKED	YY-MM-DD									
	ENGRG	YY-MM-DD	SIZE B					DWG NO *****		REV **	
	ISSUED		SCALE 1:1							SHEET 1 OF 1	



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DESIGNED BY SOFER  
www.sofer.com.cn  
Tel : +86 21 - 6482 6908  
Mail: design@sofer.com.cn

LAYER:  
FAB DARWING & DRILL LEGEND

DESIGNER: Shelley

DATE: 2017.09.12

COMPANY NAME:

ST

PROJECT NAME:

MB1350

PROJECT NUMBER:

D031-026A2

REV

B